

In the Claims:

Please cancel Claims 8, 10, 12-16 and 31-36, without prejudice, and amend

Claims 1, 3 and 5 as follows:

- B10 C1*
- B4*
- B2*
- B5*
- B6*
- B10 C2*
- B6*
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1. (Once Amended) An embedded electroconductive layer comprising:
a depressed part formed in an insulating film on a substrate;
a barrier layer covering said depressed part;
a metal growth promoting layer on said barrier layer, said metal growth
promoting layer being made of a material different from that of said barrier layer; and
an electroconductive layer embedded in said depressed part via said
barrier layer and said metal growth promoting layer.

- B10 C2*
- B5*
- B6*
- B10 C2*
- B6*
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3. (Twice Amended) The embedded electroconductive layer according to
claim 1 wherein said metal growth promoting layer is a TiN layer containing oxygen at a
lower concentration than said barrier layer.

- B10 C2*
- B6*
- B10 C2*
- B6*
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5. (Once Amended) An embedded electroconductive layer comprising:
a depressed part formed in an insulating layer on a substrate;
a ground layer containing oxygen at a high concentration in the lower
part thereof and at a low concentration in the upper part thereof due to removal of oxygen